

Common-mode chokes, ring core 4.7 ... 10 mH, 200 ... 300 mA, 60 °C

Series/Type: B82794C2

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B82794C2

Common-mode chokes, ring core

SMD

Rated voltage 42 V AC/80 V DC Rated inductance 4.7 mH to 10 mH Rated current 200 mA to 300 mA

Construction

- Current-compensated ring core quad choke
- Ferrite core
- LCP case (UL 94 V-0)
- Silicone potting
- Bifilar winding

Features

- Suitable for reflow soldering
- RoHS-compatible

Function

Suppression of asymmetrical interference coupled in on lines, whereas data signals up to some MHz can pass unaffectedly

Applications

- Telecom interfaces
- ISDN systems

Terminals

- Base material CuSn6
- Layer composition Ni, Sn
- Hot-dipped

Marking

- Marking on component:
 Manufacturer, ordering code inductance, graphic symbol,
 date of manufacture (YMMD)
- Minimum data on reel:
 Manufacturer, ordering code,
 L value, current, quantity, date of packing

Delivery mode and packing unit

- 24-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 350 pcs./reel

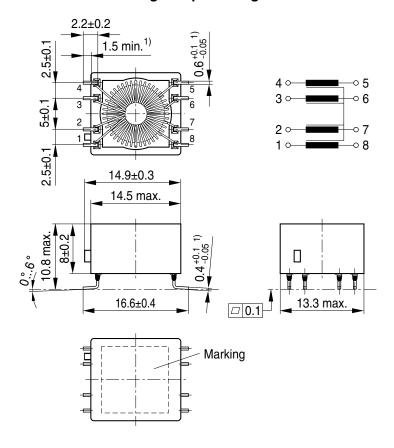




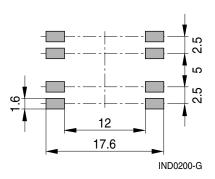
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Dimensional drawing and pin configuration



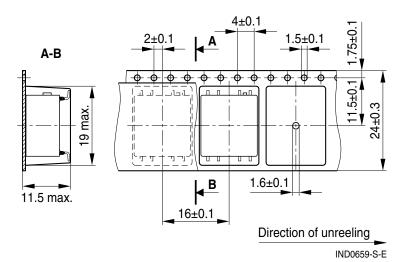
Layout recommendation



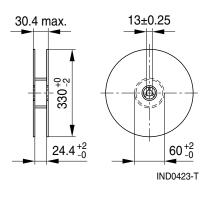
1) Soldering area IND0199-K-E Dimensions in mm

Taping and packing

Blister tape



Reel



Dimensions in mm



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Technical data and measuring conditions

42 V AC (50/60 Hz) / 80 V DC				
60 °C				
Referred to 50 Hz and rated temperature				
Measured with Agilent 4284A at 10 kHz, 50 mV, 20 °C Inductance is specified per winding.				
-30%/+50% at 20 °C				
< 10% at DC magnetic bias with I _R , 20 °C				
Measured with Agilent 4284A at 10 kHz, 50 mV, 20 °C, typical values				
Measured at 20 °C, typical values, specified per winding				
Sn96.5Ag3.0Cu0.5: (245 ± 5) °C, (3 ± 0.3) s Wetting of soldering area $\geq 95\%$ (to IEC 60068-2-58)				
(260 ±5) °C, (10 ±1) s (to IEC 60068-2-58)				
40/125/56 (to IEC 60068-1)				
–25 °C +40 °C, ≤ 75% RH				
Approx. 2.5 g				

Characteristics and ordering codes

L _R	L _{stray,typ}	I _R	R _{typ}	V _{test}	Ordering code
mH	nH	mA	mΩ	V DC, 2 s	
4.7	350	300	900	750	B82794C2475N465
10	900	200	1400	750	B82794C2106N465



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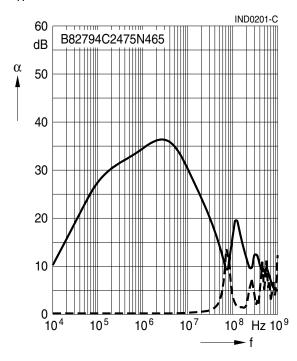
SMD

Insertion loss α (typical values at |Z| = 50 Ω , 20 °C)

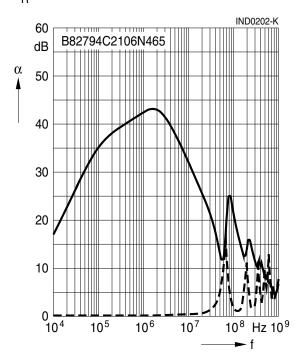
asymmetrical, all branches in parallel (common mode)

- - - - - - symmetrical (differential mode)

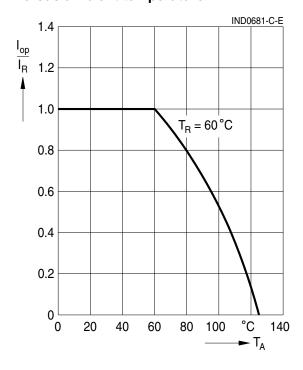
$$L_R = 4.7 \text{ mH}$$



$$L_R = 10 \text{ mH}$$



Current derating I_{op}/I_R versus ambient temperature



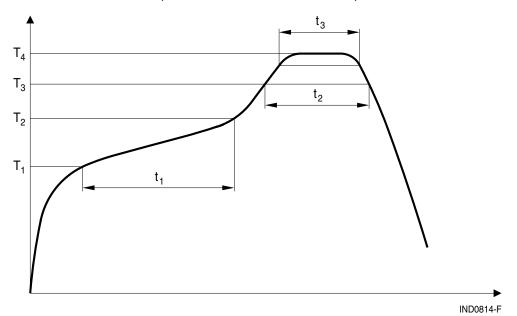
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Recommended reflow soldering curve

Pb-free solder material (based on JEDEC J-STD 020C)



T ₁ °C	T ₂ °C	T ₃ °C	T ₄ °C	t ₁	t ₂	t ₃
150	200	217	245	< 110	< 90	< 30 @ T ₄ –5 °C

Time from 25 $^{\circ}$ C to T₄: max 300 s Maximal numbers of reflow cycles: 3



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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